

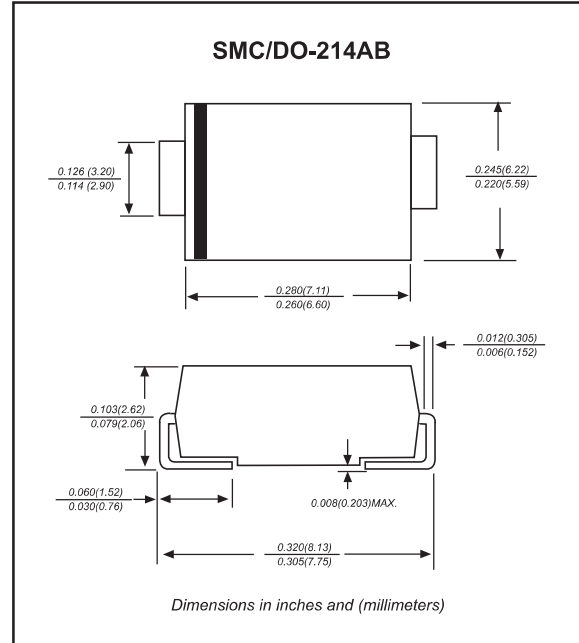
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ◆ Glass passivated chip junction
- ◆ Compliant to RoHS Directive 2011/65/EU

### Mechanical data

- ◆ **Case:** JEDEC DO-214AB molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	$I_O$			3.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC method)	$I_{FSM}$			80	A
Reverse current	$V_R = V_{RRM}$ $T_A = 25^\circ\text{C}$	$I_R$			5.0	$\mu\text{A}$
	$V_R = V_{RRM}$ $T_A = 100^\circ\text{C}$				50	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		40		$^\circ\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		40		pF
Storage temperature		$T_{STG}$	-55		+150	$^\circ\text{C}$

**Note:** 1.P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J$ , ( $^\circ\text{C}$ )
S3AC	50	35	50	1.10	-55 to +150
S3BC	100	70	100		
S3DC	200	140	200		
S3GC	400	280	400		
S3JC	600	420	600		
S3KC	800	560	800		
S3MC	1000	700	1000		

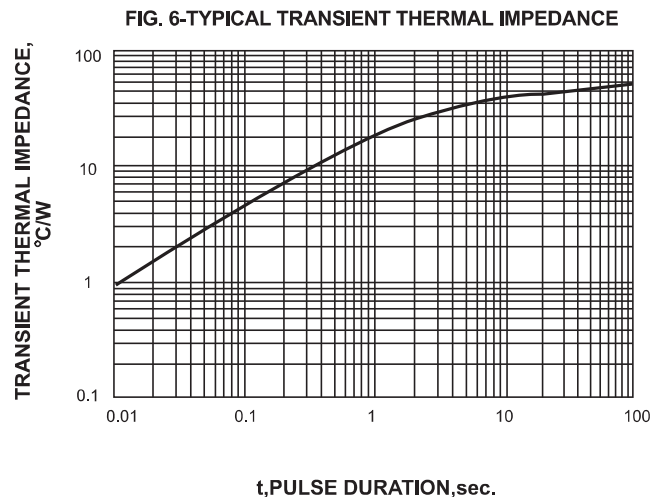
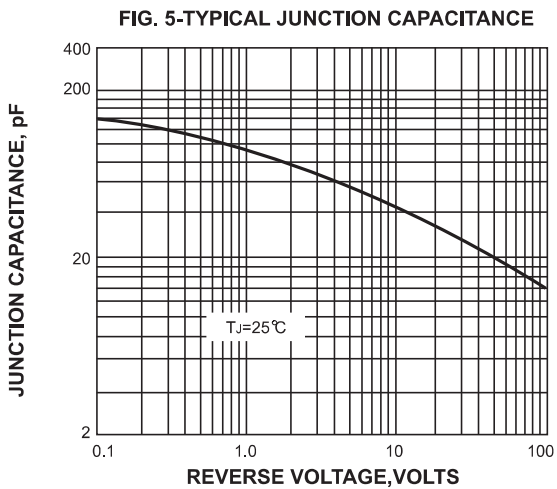
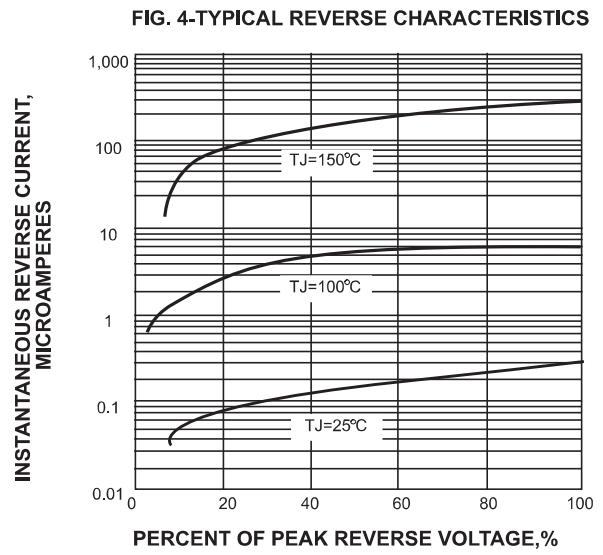
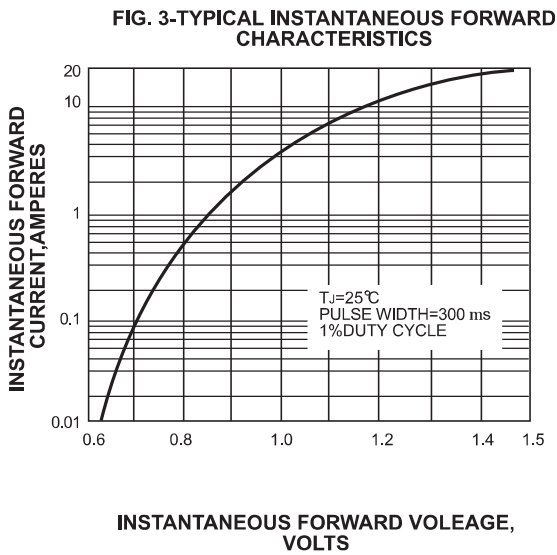
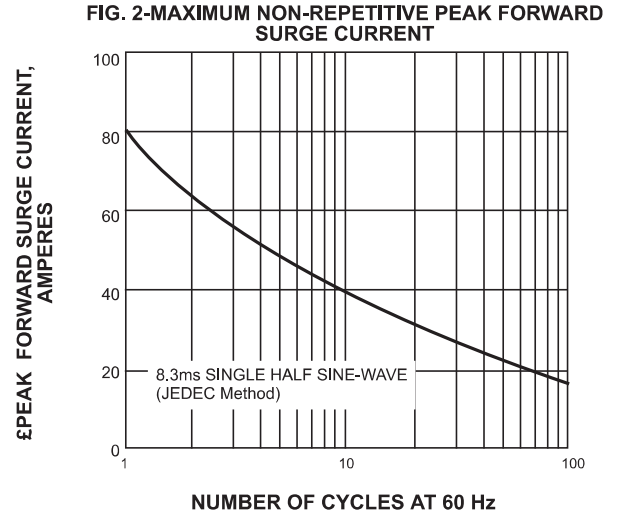
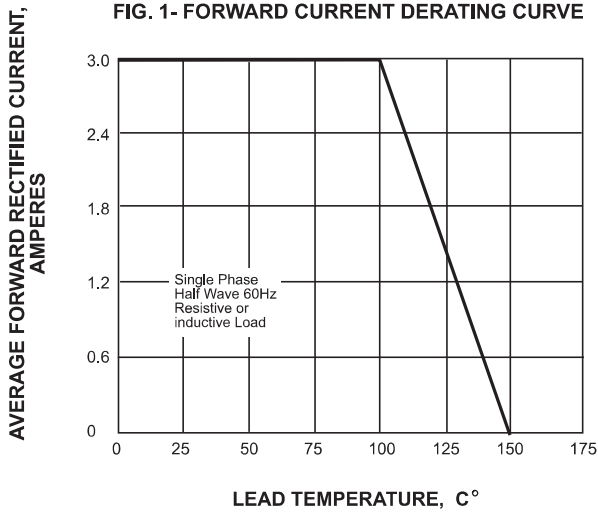
\*1 Repetitive peak reverse voltage

\*2 RMS voltage



\*3 Continuous reverse voltage

\*4 Maximum forward voltage@ $I_F=3.0\text{A}$

### Rating and characteristic curves



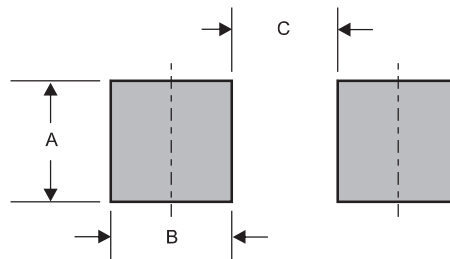
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
S3AC	S3A
S3BC	S3B
S3DC	S3D
S3GC	S3G
S3JC	S3J
S3KC	S3K
S3MC	S3M

## Suggested solder pad layout

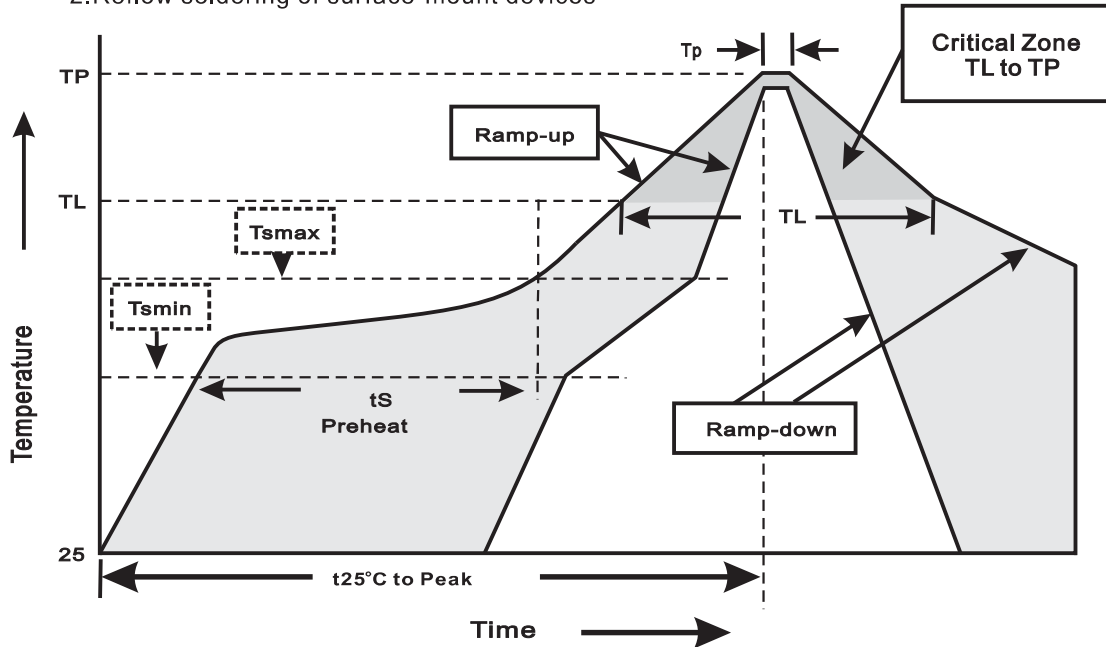


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC	0.132 (3.30)	0.100 (2.50)	0.176(4.40)

### Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



### 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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